



# PRODUCT INFORMATION LETTER

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PIL IPD-DIS/13/8035  
Dated 29 Jul 2013

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**SO8 Super High Density leadframe qualification in ST  
in-house China plant**

Sales Type/product family label	Protection
Type of change	Package assembly process change
Reason for change	To optimize industrial process
Description	Implementation of Super High Density frame with die Attach pad optimization on products housed in SO8 package -The changed products do not present modified electrical, dimensional or thermal parameters, leaving unchanged the current information published in the product datasheet -The Moisture Sensitivity Level of the part (according to the IPC/JEDEC JSTD-020D standard) remains unchanged. -The footprint recommended by ST remains the same. -There is no change neither in the packing modes nor the standard delivery quantities.
Forecasted date of implementation	22-Aug-2013
Forecasted date of samples for customer	22-Jul-2013
Forecasted date for <b>STMicroelectronics</b> change Qualification Plan results availability	22-Jul-2013
Involved ST facilities	ST in-house China plant

## DOCUMENT APPROVAL

Name	Function
Paris, Eric	Marketing Manager
Nopper, Christian	Product Manager
Cazaubon, Guy	Q.A. Manager

<h2><b>PIL</b></h2> <h3><b>Product/Process Information Letter</b></h3>			
<b>SO8 Super High Density leadframe qualification in ST in-house China plant</b>			
<b>Notification number:</b>	IPD-DIS/13/8035	<b>Issue Date</b>	22/07/2013
<b>Issued by</b>	Aline AUGIS		
<b>Product series affected by the change</b>	CLP190ERL CLP30-200B1RL ETP01-1621RL ETP01-2821RL LCDP1521RL LCDP1521SRL LCP1521S LCP1521SRL LCP1531RL PEP01-5841 QPS200BRL THBT15011DRL THBT20011D/DRL TPI12011N/NRL TPI8011N/NRL TPN3021/RL TPP25011RL		
<b>Reason for change</b>			
ST upgrades its products housed in SO8 package with a new Super High Density frame in order to optimize its industrial process.			
<b>Effects of change</b>			
Implementation of Super High Density frame with die Attach pad optimization on products housed in SO8 package <ul style="list-style-type: none"> <li>▪ The changed products do not present modified electrical, dimensional or thermal parameters, leaving unchanged the current information published in the product datasheet</li> <li>▪ The Moisture Sensitivity Level of the part (according to the IPC/JEDEC JSTD-020D standard) remains unchanged.</li> <li>▪ The footprint recommended by ST remains the same.</li> <li>▪ There is no change neither in the packing modes nor the standard delivery quantities.</li> </ul>			

(1) IPD: Industrial & Power Discretes - ASD: Application Specific Device – IPAD™: Integrated Passive and Active Devices

**Product identification and traceability**

Traceability and identification is ensured by:

- Specific **internal product codification** for devices with Super High Density leadframe. This code is mentioned on the inner and outer packing box.
- **QA lot number** .

**Qualification complete date**

8<sup>th</sup> of April, 2013

**Forecasted sample availability**

Product family	Package	Commercial part Number	Availability date
Protection	SO8	LCP1521S	Now
Protection	SO8	TPN3021	Now
Protection	SO8	LCP1531	Now
Protection	SO8	TPI12011NRL	Now
Protection	SO8	TPI8011NRL	Now
Protection	SO8	PEP01-5841	Now

**Change implementation schedule**

Sales types	Estimated production start	Estimated first shipments
All SO8	Week 30-2013	Week 34-2013

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